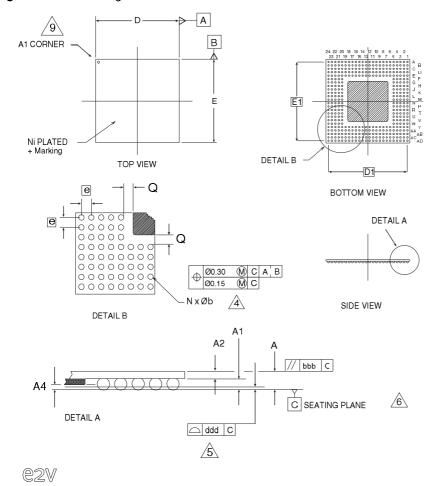
Package Information

Figure 8-1. Package Outline



DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
Α	1.25	1.45	1.60
A1	0.50	0.60	0.70
D	30.80	31.00	31.20
D1	29.21 (BSC.)		
E	30.80	31.00	31.20
E1	29.21 (BSC.)		
b	0.70	0.80	0.90
A2	0.75	0.85	0.95
М	24		
Ν	380		
bbb			0.25
ddd			0.20
е	1,27 TYP.		
A4	0.15		
Q	1.1		
REF: JEDEC MS-034B VARIATION BAK-1			

- 1. All dimensions are in millimeters.
- An uniterisions are in millimeters.
 "e" represents the Basic Solder Ball Grid Pitch.
 "M" represents the Basic Solder Ball matrix size, and symbol "N" is the maximum allowable number of balls after depopulating.
- Dimension "b" is measured at the maximum solder ball diameter parallel to primary Datum C.
- Dimension "ddd" is measured parallel to primary Datum C.
- Primary Datum C and seating plane are defined by the spherical crowns of the solder balls.
- 7. Package surface shall be Ni plated.
- 8. Encapsulant Size may vary with die size.
- Small round depression for Pin 1 identification.
- 10. "A4" is measured at the edge of encapsulant to the Inner edge of ball pad.
- 11. Dimensioning and tolerancing Per Asme Y14.5 1994
- 12. This drawing is for qualification purpose only.